

RoHS

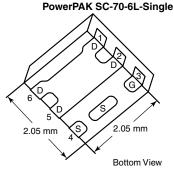
COMPLIANT

HALOGEN FREE

Vishay Siliconix

N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω) Max.	Max. I _D (A) ^a Q _g (Ty			
100	0.083 at V _{GS} = 10 V	11.3	3.5 nC		
	0.130 at V _{GS} = 4.5 V	9	3.5110		



Ordering Information:

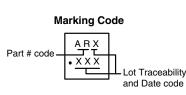
SiA416DJ-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- TrenchFET[®] Power MOSFET
- 100 $\%~\text{R}_{g}$ and UIS Tested
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- DC/DC Converters
- Full-Bridge Converters
- For Power Bricks and POL Power





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	S (T _A = 25 °C, unle	ess otherwise not	ed)		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	100	V		
Gate-Source Voltage		V _{GS}	± 20	v	
Continuous Drain Current (T _J = 150 °C)	T _C = 25 °C		11.3		
	T _C = 70 °C		9		
	T _A = 25 °C	I _D	4.8 ^{b, c}		
	T _A = 70 °C		3.9 ^{b, c}		
Pulsed Drain Current (t = 300 μs)		I _{DM}	15	A	
Cantinuaus Courses Drain Diada Current	T _C = 25 °C		12		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	2.9 ^{b, c}		
Single Pulse Avalanche Current		I _{AS}	3		
Single Pulse Avalanche Energy	Pulse Avalanche Energy L = 0.1 mH		0.45	mJ	
Maximum Power Dissipation	T _C = 25 °C		19		
	T _C = 70 °C		12		
	T _A = 25 °C	P _D	3.5 ^{b, c}	W	
	T _A = 70 °C		2.2 ^{b, c}		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	**		
Soldering Recommendations (Peak Temperature) ^{d, e}			260		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, f}	$t \le 5 s$	R _{thJA}	28	36	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	5.3	6.5		

Notes:

a. Based on T_C = 25 °C.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

f. Maximum under steady state conditions is 80 °C/W.

Document Number: 63649 For technical questions, contact: pmostechsupport@vishay.com S12-2438-Rev. B, 15-Oct-12

Vishay Siliconix



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					•		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	100			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		54		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \ \mu A$		- 4.4			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.6		3	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55 ^{\circ}\text{C}$			1 10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	10		-	A	
	D(01)	$V_{GS} = 10 \text{ V}, I_D = 3.2 \text{ A}$		0.068	0.083		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 2.6 \text{ A}$		0.092	0.130	Ω	
Forward Transconductance ^a	9 _{fs}	$V_{\rm DS} = 10 \text{ V}, \text{ I}_{\rm D} = 3.2 \text{ A}$		8		S	
Dynamic ^b	513			1 -	l	-	
Input Capacitance	C _{iss}			295		[
Output Capacitance	C _{oss}	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz		92		pF	
Reverse Transfer Capacitance	C _{rss}			16			
		V _{DS} = 50 V, V _{GS} = 10 V, I _D = 4.8 A		6.5	10		
Total Gate Charge	Qg			3.5	5.3		
Gate-Source Charge	Q _{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 4.8 \text{ A}$		1.2		nC	
Gate-Drain Charge	Q _{gd}	20 00 2		1.9			
Output Charge	Q _{oss}	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}$		7.6			
Gate Resistance	R _g	f = 1 MHz	0.4	1.8	3.6	Ω	
Turn-On Delay Time	t _{d(on)}			5	10		
Rise Time	t _r	V_{DD} = 50 V, R_L = 12.8 Ω		13	25	-	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong$ 3.9 A, V_GEN = 10 V, R_g = 1 Ω		10	20		
Fall Time	t _f			10	20		
Turn-On Delay Time	t _{d(on)}			25	50	ns	
Rise Time	t _r	V_{DD} = 50 V, R_L = 12.8 Ω		100	200	-	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong$ 3.9 A, V_GEN = 4.5 V, R_g = 1 Ω		15	30		
Fall Time	t _f			25	50		
Drain-Source Body Diode Characteristic	cs					I	
Continuous Source-Drain Diode Current	ا _S	$T_{C} = 25 \ ^{\circ}C$			12	•	
Pulse Diode Forward Current ^a	I _{SM}				15	A	
Body Diode Voltage	V _{SD}	I _S = 3.9 A		0.85	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			30	60	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	L = 2.0.4 dl/dt = 100.4/vs T = 05.00		30	60	nC	
Reverse Recovery Fall Time	t _a	$I_F = 3.9 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, \text{ T}_J = 25 ^\circ\text{C}$		20			
Reverse Recovery Rise Time	t _b	-		10		ns	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

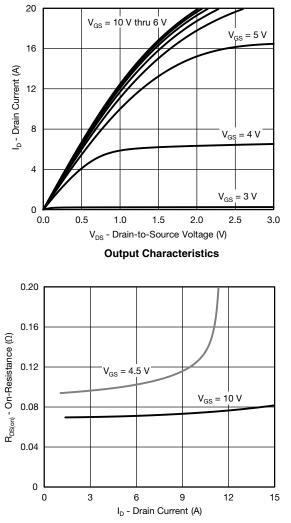
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Document Number: 63649 S12-2438-Rev. B, 15-Oct-12

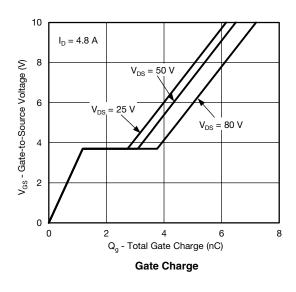


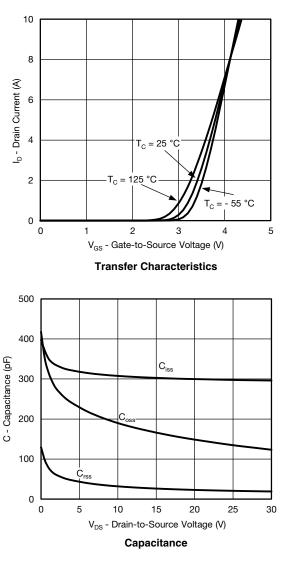
SiA416DJ Vishay Siliconix

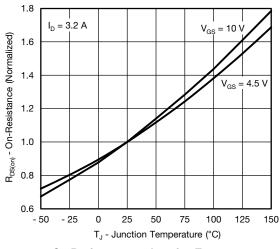
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



On-Resistance vs. Drain Current and Gate Voltage







On-Resistance vs. Junction Temperature

For technical questions, contact: pmostechsupport@vishay.com

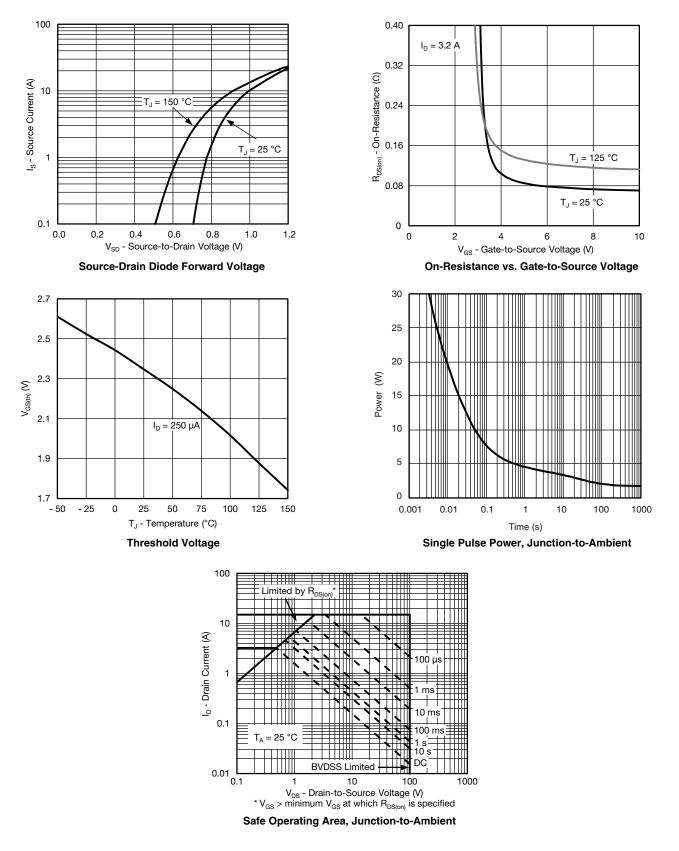
www.vishay.com

3



Vishay Siliconix

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

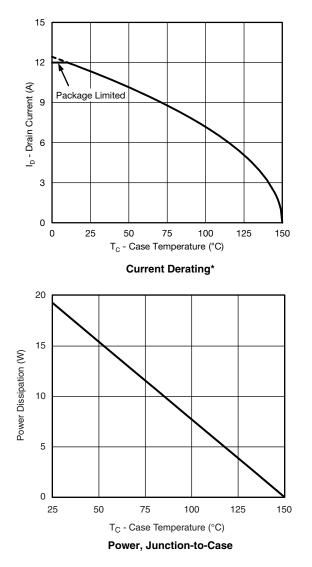


For technical questions, contact: pmostechsupport@vishay.com

Document Number: 63649 S12-2438-Rev. B, 15-Oct-12



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



* The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

Vishay Siliconix

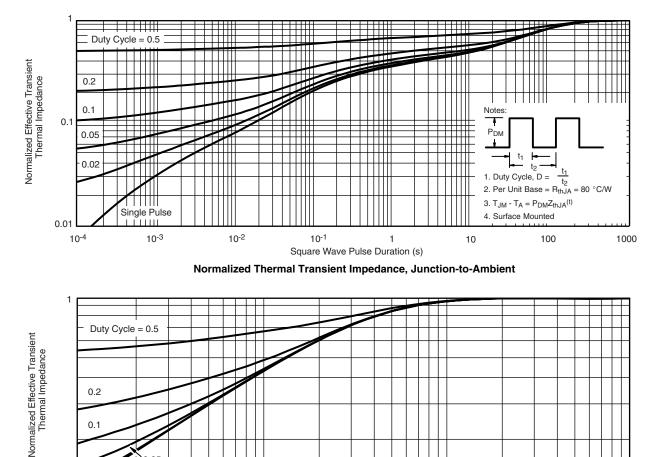


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

0.05

0.02 Single Pulse

0.1



10⁻³

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <u>www.vishay.com/ppg?63649</u>.

Square Wave Pulse Duration (s) Normalized Thermal Transient Impedance, Junction-to-Case

10-2

www.vishay.com 6 For technical questions, contact: pmostechsupport@vishay.com

Document Number: 63649 S12-2438-Rev. B, 15-Oct-12

10⁻¹



PowerPAK[®] SC70-6L

VISHA

b PIN2 PIN1 PIN3 _ ₹



b

PIN3

__ ₿

PIN2

PIN1

¥

Vishay Siliconix

¹



RECOMMENDED PAD LAYOUT FOR PowerPAK[®] SC70-6L Single



Dimensions in mm/(Inches)

Return to Index



Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.